



# Thin Film MΩ Center-Tap Chip Resistor Divider Network



Product may not be to scale

The CTM resistor chips extends the resistance range to 10M in a center tap configuration while keeping the die size relatively small.

The CTMs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The CTMs are 100 % electrically tested and visually inspected to MIL-STD-883, method 2032 class H or K.

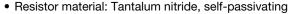
#### **FEATURES**

- Wire bondable
- Resistance range total: 200 k $\Omega$  to 10 M $\Omega$



• Chip size: 0.040" x 0.040"

• Case: 0404



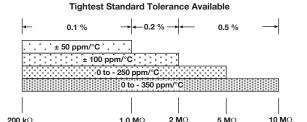
• Moisture resistant

#### **APPLICATIONS**

Vishay EFI CTM tapped megohm resistor chips are designed for hybrid packages requiring high value, two resistor combinations.



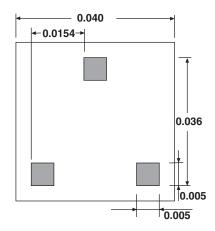
TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES, AND TOLERANCES		
PARAMETER	VALUE	UNIT
Total Resistance Range	200K to 10M	Ω
Standard Tolerances	± 0.1, ± 0.2, ± 0.5	%
TCR	± 50, ± 100, 0, - 250, - 350	ppm/°C



STANDARD ELECTRICAL SPECIFICATIONS		
PARAMETER	VALUE	UNIT
TCR Tracking Between Resistors	± 5	ppm/°C
Ratio/Ratio, R <sub>A</sub> /R <sub>B</sub> : Tolerance	1 ± 1 standard	%
Noise	- 12 typ.	dB
Moisture Resistance, MIL-STD-202, Method 106	± 0.5 max. Δ <i>R/R</i>	%
Otabilita 1000 b 1105 % 10 m/W	± 0.5 max. absolute	0/
Stability, 1000 h, + 125 °C, 10 mW	± 0.005 ratio	%
Operating Temperature Range	- 55 to + 125	°C
Thermal Shock, MIL-STD-202, Method 107, Test Condition F	± 0.25 max. Δ <i>R</i> / <i>R</i>	%
High Temperature Exposure, + 150 °C, 100 h	± 0.5 max. Δ <i>R/R</i>	%
Dielectric Voltage Breakdown	200	V
Insulation Resistance	10 <sup>12</sup> min.	Ω
Operating Voltage	100 max.	V
DC Power Rating at + 70 °C (derated to zero at + 175 °C)	0.02 max.	W
5 x Rated Power Short-Time Overload, + 25 °C, 5 s	± 0.25 max. Δ <i>R</i> / <i>R</i>	%



#### **DIMENSIONS** in inches

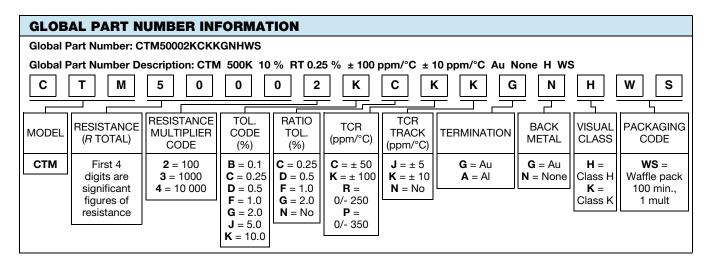


#### **SCHEMATIC**

$$R_{T} = R_{A} + R_{B}$$

$$R_{A} \qquad R_{B}$$

MECHANICAL SPECIFICATIONS	
PARAMETER	VALUE
Chip Size	0.040" x 0.040" ± 0.002" (1.02 mm x 1.02 mm ± 0.05 mm)
Chip Thickness	0.010" ± 0.002" (0.254 mm ± 0.05 mm)
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO <sub>2</sub>
Resistor Material	Tantalum nitride, self-passivating
Bonding Pad Size	0.005" x 0.005" (0.127 mm x 0.127 mm) min.
Number of Pads	3
Pad Material	10 kÅ minimum gold (Al optional)
Backing	None, lapped semiconductor silicon (Au optional)





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Vishay

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